

IDEAS GENERATED DRAWING, DO NOT CHANGE BY HAND.

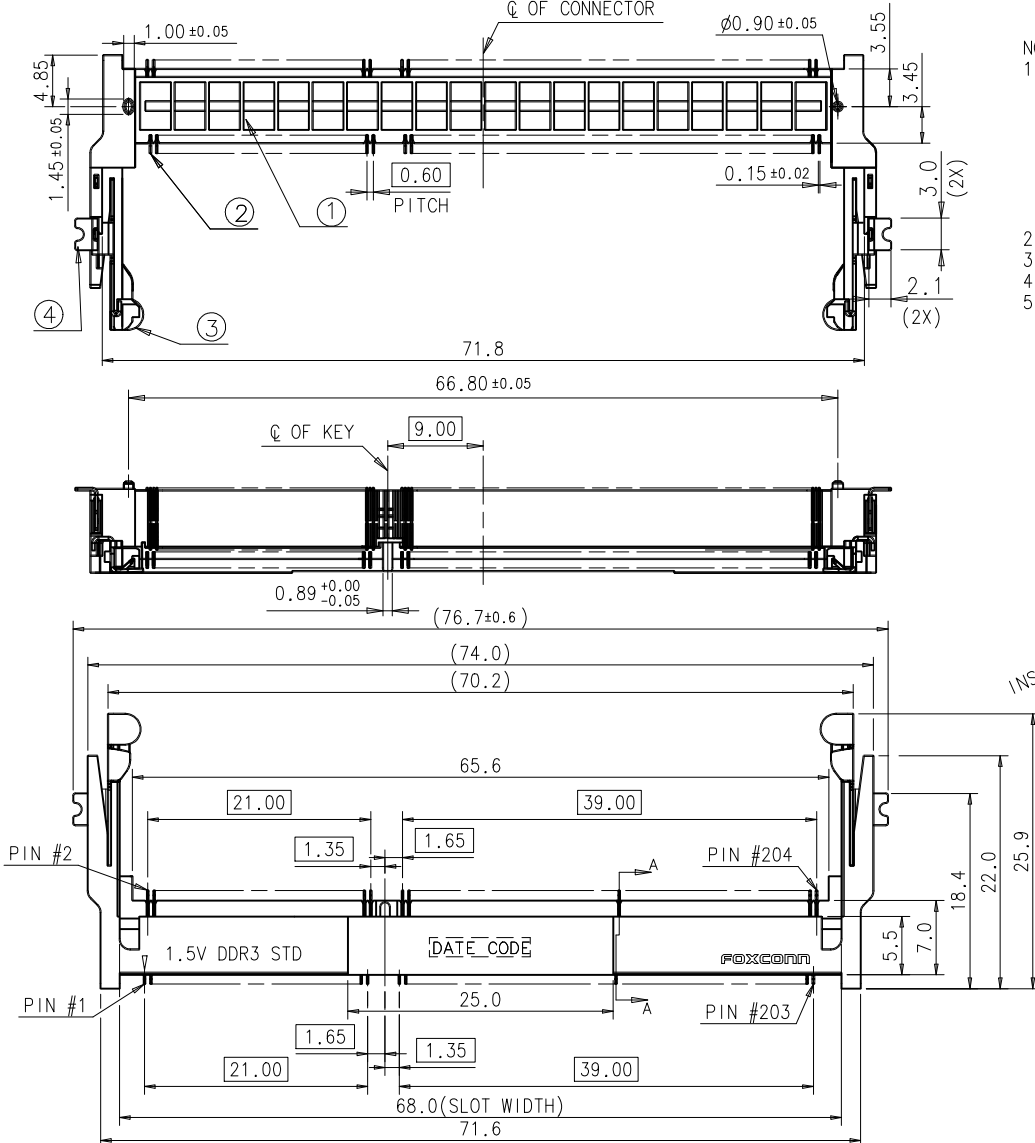
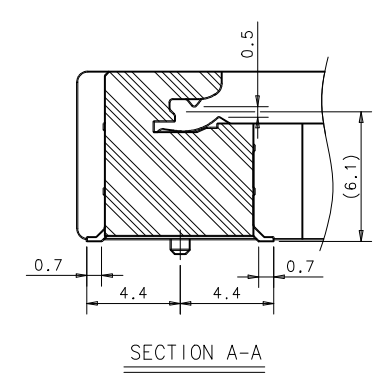
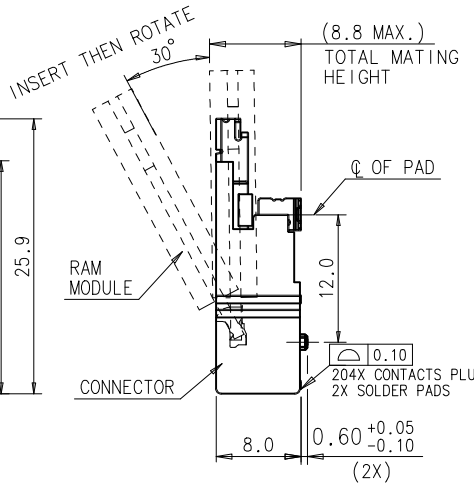
G	BC-14-0008184	C.S Li	REV.	ECN. NO.	APPD.
H	BC-14-0010507	C.S Li	A	BC-10-0100061	Herry Yang
			B	BC-11-0038722	Herry Yang
			C	BC-11-0049137	Herry Yang
			D	BC-11-0119946	Herry Yang
			E	BC-13-0004440	C.S Li
			F	BC-13-0087027	C.S Li

NOTES:

- ELECTRICAL CHARACTERISTICS:
  - CONTACT CURRENT RATING: 0.5 AMPERE MAX. PER PIN.  
(PER PIN) DOESN'T EXCEED 30°C ABOVE AMBIENT AT 0.5 AMPERE MAX. PER PIN.
  - VOLTAGE RATING: 25V AC.
  - INSULATION RESISTANCE: 100 MEGAOHMS MIN. AT 500V DC.
  - DIELECTRIC WITHSTANDING VOLTAGE: 250V AC RMS AT 60Hz, FOR 1 MINUTE.
  - CONTACT RESISTANCE: 50 MILLIOHMS MAX. PER PIN INITIAL.  
60 MILLIOHMS MAX. PER PIN AFTER FULL ENVIRONMENTAL TESTING.
- MECHANICAL CHARACTERISTICS: DURABILITY: 60 MATING CYCLES.
- OPERATION TEMPERATURE: -55°C TO +85°C.
- RECOMMENDED PROCESS CONDITION: SMT, PEAK TEMPERATURE: 260°C, 10~20S.
- PLEASE CONTACT FOXCONN SALES REPRESENTATIVE TO VERIFY PRODUCT DETAIL & AVAILABILITY.

PART NO. DESCRIPTION: A S O A6 2 \* - H 8 S N - \* H

- MEMORY MODULE SOCKET
  - HORIZONTAL TYPE
  - SINGLE ROW
  - NO. OF POS.
  - A6 = 204 POS.
  - SMT
- CONTACT AREA PLATING
  - 1=GOLD FLASH
  - Y=5u\* GOLD PLATING
  - 6=10u\* GOLD PLATING
  - 7=15u\* GOLD PLATING
  - 3=30u\* GOLD PLATING
- H=HALOGEN FREE & LEAD FREE
  - 4=SOFT TRAY
  - 7=TAPE REEL
  - N=GENERAL TYPE
  - S=STANDARD
  - 8=8.0mm HEIGHT
  - DDR III SO DIMM



ITEM	DESCRIPTION	Q'TY	MATERIAL	TREATMENT
④	METAL PAD	2	COPPER ALLOY	50u* NICKEL UNDER PLATING OVER ALL 2u* Pd PLATING OVER SOLDER AREA
③	METAL SPRING	2	COPPER ALLOY	50u* NICKEL PLATING OVER ALL
②	CONTACT	204	COPPER ALLOY	50u* NICKEL UNDER PLATING GOLD FLASH AT TAIL GOLD FLASH OR 5u* OR 10u* OR 15u* OR 30u* GOLD PLATING AT CONTACT AREA
①	HOUSING	1	THERMOPLASTIC	UL94V-0, HALOGEN-FREE, IVORY COLOR

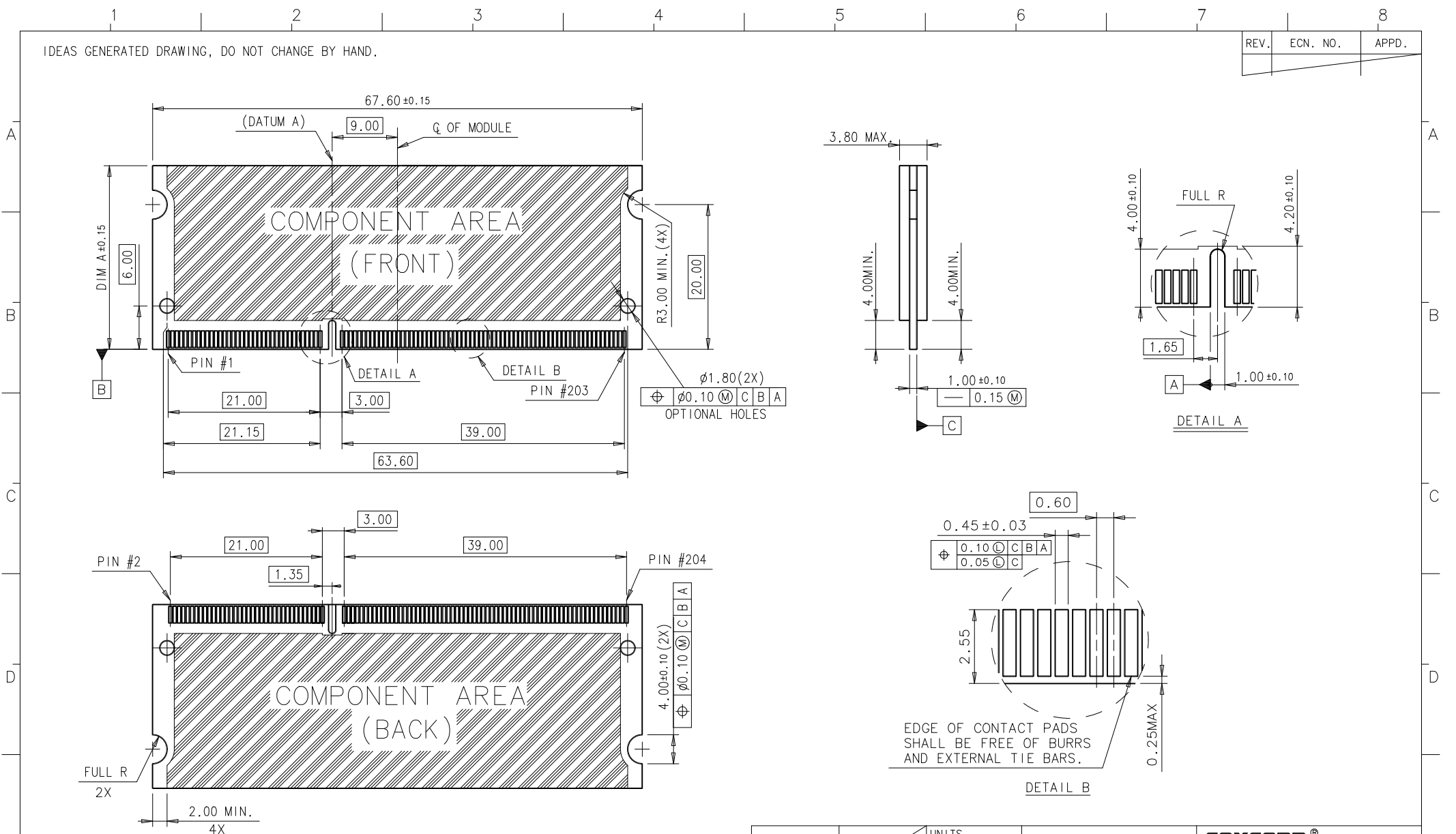
X. ± 0.30	X° ±	UNITS	mm
.X ± 0.25	.X° ±	MAT'L	
.XX ± 0.15	.XX° ±	FINISH	
.XXX ±	.XXX° ±	Q'TY	

THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED, AND SHALL NOT BE REPRODUCED, COPIED OR USED IN ANY MANNER WITHOUT THE PRIOR WRITTEN CONSENT OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED.

NAME (INTENDED USE)	FOXCONN®
DDR III SO DIMM CONNECTOR	FOXCONN INTERCONNECT TECHNOLOGY LIMITED.
PART NO. (INTENDED USE)	CLASS: □CONFIDENTIAL □SECRET ■GENERAL
ASOA62*-H8SN-*H	TITLE: CUSTOMER DRAWING
APPD: C.S Li	DWG NO.: 317-0000-1996
CHKD: ZH Wang	SCALE SHEET REV.
DR: Wang Justin 3/5/14	N/A 1/5 H

IDEAS GENERATED DRAWING, DO NOT CHANGE BY HAND.

REV.	ECN. NO.	APPD.



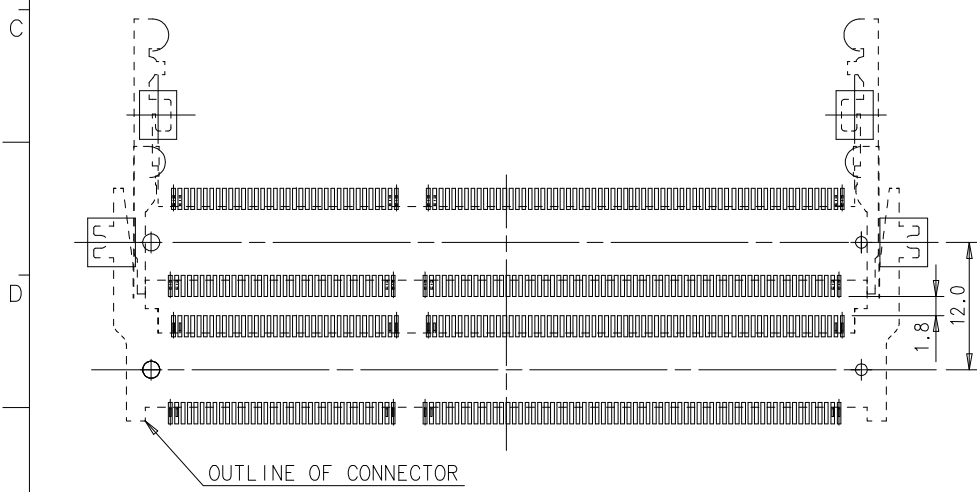
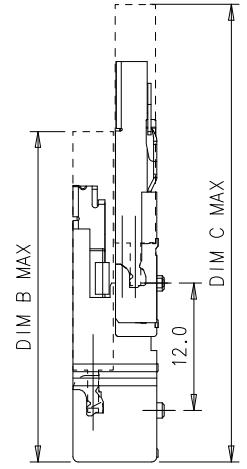
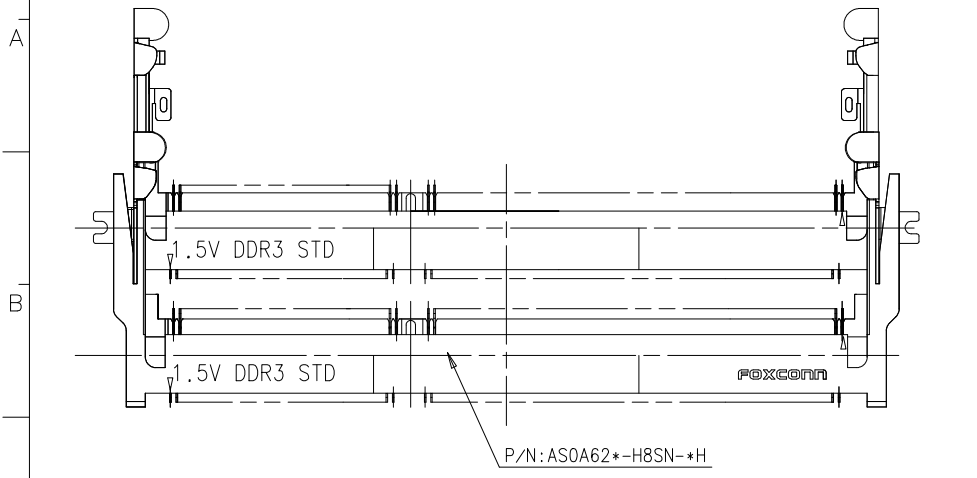
DDR III SO-DIMM MODULE BOARD LAYOUT

SDRAM VARIATIONS	DIM A
TYPE 1	25.40
TYPE 2	31.75
TYPE 3	30.00

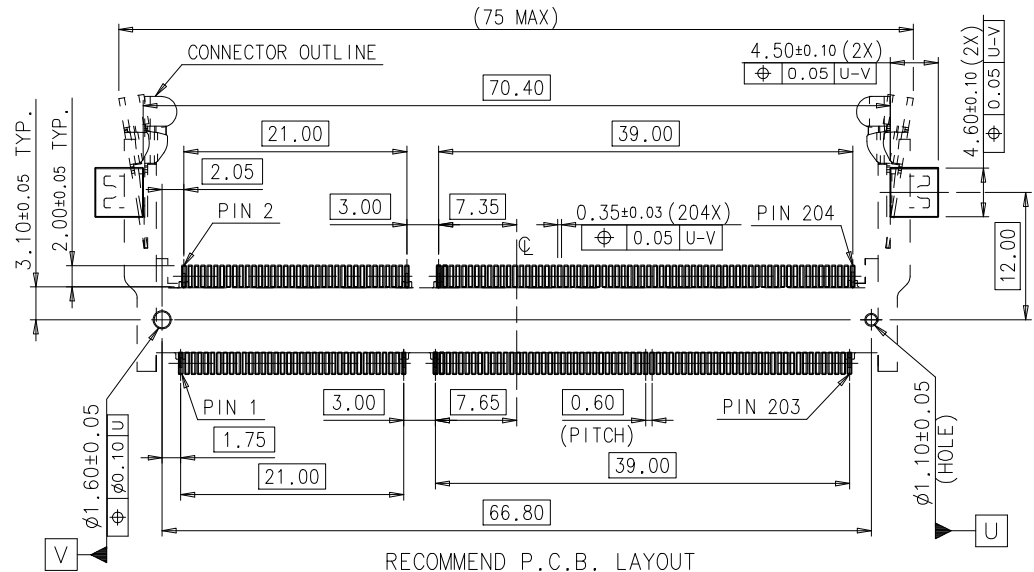
X. ± 0.25	X° ±	UNITS mm	NAME (INTENDED USE)	<b>FOXCONN®</b>
.X ± 0.10	.X° ±	MAT'L	DDR III SO DIMM CONNECTOR	FOXCONN INTERCONNECT TECHNOLOGY LIMITED.
.XX ± 0.05	.XX° ±	FINISH	PART NO. (INTENDED USE)	CLASS: □CONFIDENTIAL □SECRET ■GENERAL
.XXX ±	.XXX° ±		AS0A62*-H8SN-*H	TITLE: CUSTOMER DRAWING
THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED, AND SHALL NOT BE REPRODUCED, COPIED OR USED IN ANY MANNER WITHOUT THE PRIOR WRITTEN CONSENT OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED.			APPD: C.S Li	DWG NO.:
			CHKD: ZH Wang	317-0000-1996
			DR: Wang Jusrin 3/5'14	SCALE SHEET REV.
				N/A 2/5 H

IDEAS GENERATED DRAWING, DO NOT CHANGE BY HAND.

REV.	ECN. NO.	APPD.



P.C.B. LAYOUT(STACKED ORIENTATION)



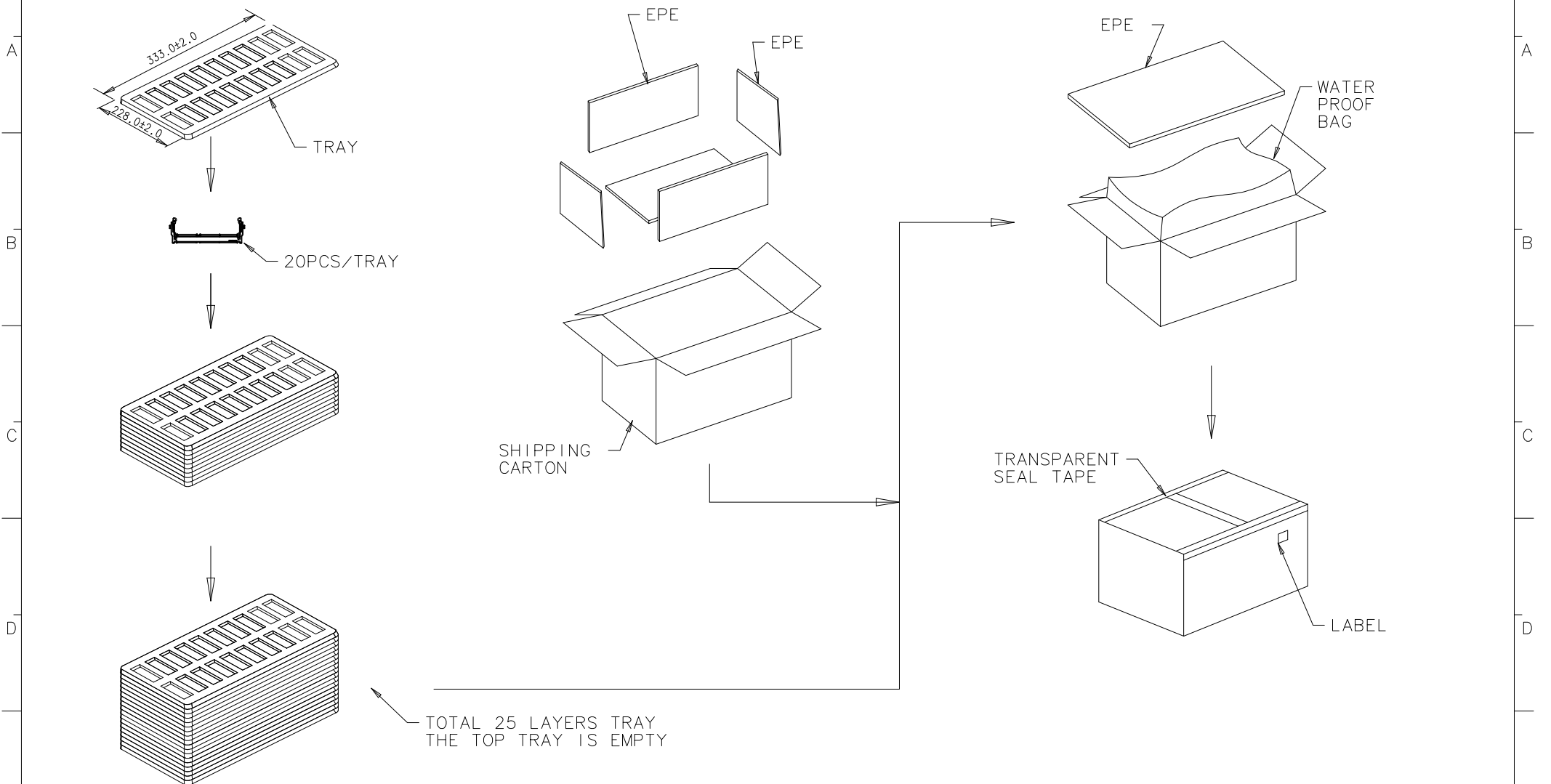
RECOMMEND P.C.B. LAYOUT

SDRAM VARIATIONS	DIM B	DIM C
TYPE 1	30.4	42.4
TYPE 2	36.7	48.7
TYPE 3	35.0	47.0

X. ± 0.25	X° ±	UNITS mm	NAME (INTENDED USE)	<b>FOXCONN®</b> FOXCONN INTERCONNECT TECHNOLOGY LIMITED.
.X ± 0.10	.X° ±		DDR III SO DIMM CONNECTOR	
.XX ± 0.05	.XX° ±	MAT'L	PART NO. (INTENDED USE)	CLASS: □CONFIDENTIAL □SECRET ■GENERAL
.XXX ±	.XXX° ±		AS0A62*-H8SN-*H	TITLE: CUSTOMER DRAWING
THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED. AND SHALL NOT BE REPRODUCED, COPIED OR USED IN ANY MANNER WITHOUT THE PRIOR WRITTEN CONSENT OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED.			APPD: C.S Li	DWG NO.:
			CHKD: ZH Wang	317-0000-1996
Q'TY			DR: Wang Justin 3/5/14	SCALE SHEET REV.
				N/A 3/5 H

IDEAS GENERATED DRAWING, DO NOT CHANGE BY HAND.

REV.	ECN. NO.	APPD.



NOTES:

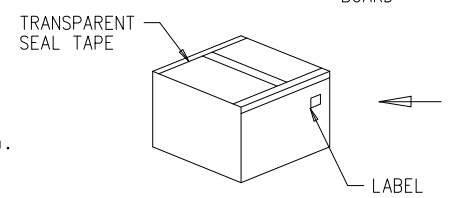
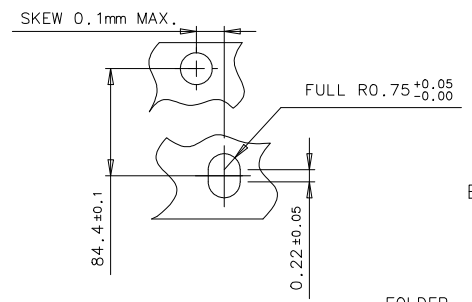
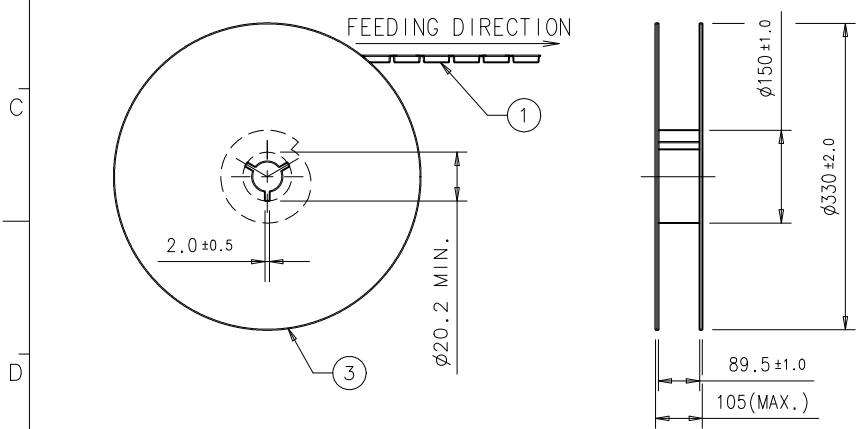
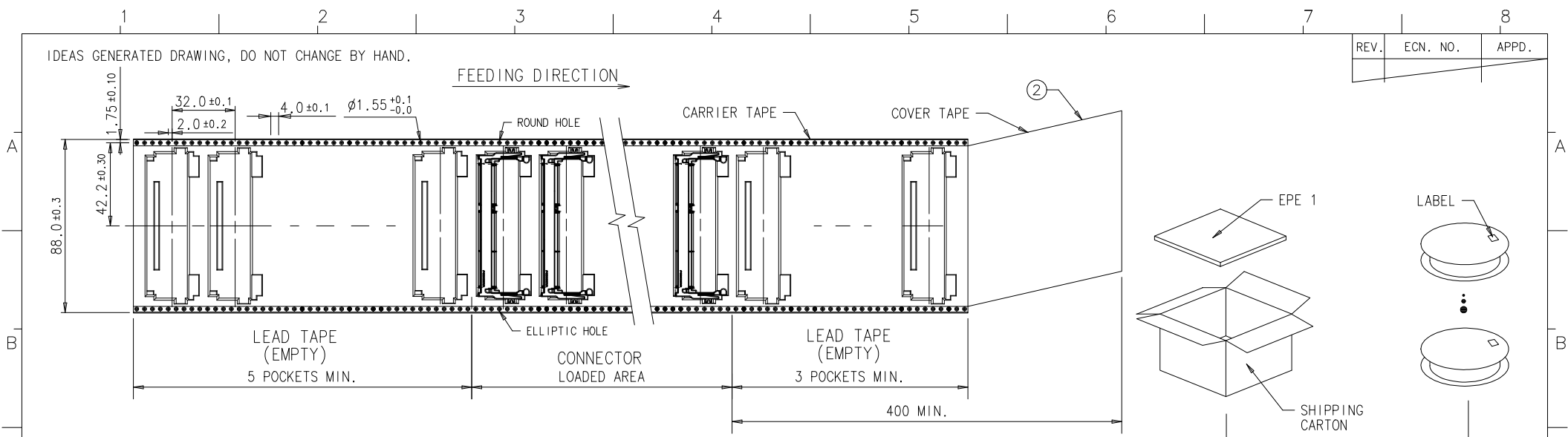
- PACKING CAPACITY : 20 PCS/TRAY, 24 TRAYS/BOX,  
TOTAL 480 PCS/BOX.

X. ± 1.5	X° ±	UNITS mm	NAME (INTENDED USE)	<b>FOXCONN®</b>
.X ± 1.0	.X° ±	MAT'L	DDR III SO DIMM CONNECTOR	FOXCONN INTERCONNECT TECHNOLOGY LIMITED.
.XX ± 0.5	.XX° ±	FINISH	PART NO. (INTENDED USE)	CLASS: □CONFIDENTIAL □SECRET ■GENERAL
.XXX ±	.XXX° ±		AS0A62*-H8SN-*H	TITLE: CUSTOMER DRAWING
THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED, AND SHALL NOT BE REPRODUCED, COPIED OR USED IN ANY MANNER WITHOUT THE PRIOR WRITTEN CONSENT OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED.			APPD: C.S Li	DWG NO.:
			QTY	CHKD: ZH Wang
			DR: Wang Justin 3/5/14	SCALE SHEET REV. N/A 4/5 H

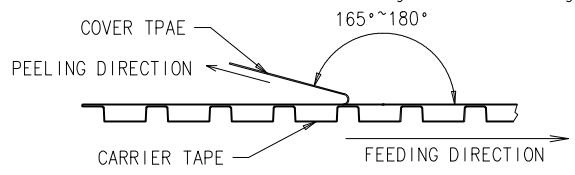
CONNECTOR P/N	AS0A62*-H8SN-4H
---------------	-----------------

IDEAS GENERATED DRAWING, DO NOT CHANGE BY HAND.

REV.	ECN. NO.	APPD.



- NOTES:  
 1. 10 POCKETS HOLE PITCH CUMULATIVE TOLERANCE ±0.20mm.  
 2. COVER TAPE PEELING STRENGTH : 0.01kgf MIN., 0.15 kgf MAX. AT 300mm/min.



3. PACKING CAPACITY : 140 PCS/REEL, 3 REELS/BOX, TOTAL 420 PCS/BOX.

③	REEL	POLYSTYRENE
②	COVER TAPE	POLYESTER
①	CARRIER TAPE	POLYSTYRENE
ITEM	DESCRIPTION	MATERIAL

X. ± 1.5	X° ±	UNITS mm	NAME (INTENDED USE)	<b>FOXCONN®</b>
.X ± 1.0	.X° ±	MAT'L	DDR III SO DIMM CONNECTOR	
.XX ± 0.5	.XX° ±	FINISH	PART NO. (INTENDED USE)	CLASS: <input type="checkbox"/> CONFIDENTIAL <input type="checkbox"/> SECRET <input checked="" type="checkbox"/> GENERAL
.XXX ±	.XXX° ±		AS0A62*-H8SN-*H	TITLE: CUSTOMER DRAWING
THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED, AND SHALL NOT BE REPRODUCED, COPIED OR USED IN ANY MANNER WITHOUT THE PRIOR WRITTEN CONSENT OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED.			APPD: C.S Li	DWG NO.:
			CHKD: ZH Wang	317-0000-1996
QTY			DR: Wang Justin 3/5/14	SCALE SHEET REV.
				N/A 5/5 H

CONNECTOR P/N	AS0A62*-H8SN-7H
---------------	-----------------

## X-ON Electronics

Largest Supplier of Electrical and Electronic Components

*Click to view similar products for [Memory Card Connectors](#) category:*

*Click to view products by [Foxconn](#) manufacturer:*

Other Similar products are found below :

[6407-249V-25273P](#) [6407-249V-25343P](#) [6426-201-21343](#) [69.920.0553.0](#) [MCR60A-98D-2.54DSA\(70\)](#) [809180410000000](#) [DM3AT-SF-PEJM5\(41\)](#) [IC11S-BUR-PNEJL\(71\)](#) [C70210M0083692](#) [2041353-2](#) [308-DS1P0811-192](#) [HM2P09PDR360N9LF](#) [10014744-011TLF](#) [11327-001](#) [11327-002](#) [NX1-32T-KT3K\(05\)](#) [95622-003LF](#) [84648-056HLF](#) [CCM03-3109 B LFT](#) [MS3116J10-6PW](#) [2309923-1](#) [61126-050CAHLF](#) [GTFP08432B1HR](#) [G85D1160022HHR](#) [SCE2MSDB76A121SN](#) [SCE2MSDZN76A121SN](#) [10014744-011ALF](#) [10014744-011LF](#) [10057542-1211FLF](#) [10067972-000LF](#) [10067972-050LF](#) [10122302-20110LF](#) [G85D1162022HHR](#) [TF-05A](#) [XKNANO-1412](#) [SMN-304-ARP6](#) [MIS11-S1F1-2000-A](#) [MCS-302S-KT1B](#) [K-DYX-008](#) [K-DYX-004](#) [SMO-1030](#) [MCS-110-KT](#) [SIM-217](#) [SNO-1355-KT](#) [SMO-1025-P10](#) [SIM-211S-P6](#) [SNO-1440](#) [SMO-1570](#) [SMO-1550](#) [SIM-212S-8P](#)